© Copyright	<b>Composition De</b> 2005. IPC, Bannock and Pan-American c	burn, Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declarati he declaration e	on of the su	bstances v all lower	within the manufactur level materials for w	rer listed ite hich the ma	m. Note: i nufacturer	f the item is an as r has engineering	sembly with low responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute						Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
Supplier Information														
Company name* Company unique ID					1	Unique ID Authority Response Date*								
onsemi										2025-07-07				
Contact Name Title			ct		Phone - Contact* Email - Contact*									
Product-Env-Stewards	Product Enviro Compliance				NA			Product-Env-Stewards@onsemi.com						
Authorized Representative* Ti			sentative	tative Phone - Representative* Email - Representative*			ative*							
Product-Env-Stewards Product			ro Compliance			NA Product-Env-Stewards@onsemi.com					m			
Requester Item Number	Requester Item Number Mfr Item		Number Mfr Item Name			Effective Date	Version	М	Manufacturing Site		eight*	UOM	Unit Type	
	MT9V0 DR1	9V022IA7ATM- 1 VGA 1/3 GS CIS		5		2025-07-07		Т	TWU		59.0	mg	Each	
Ianufacturing Proccess Inf	formation													
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 Ma				J-STD-020 MSI	Rating	Peak Proc	ess Body Te	emperature	e Max Time at Peak	Temperatu	re Numb	per of Reflow Cyc	les	
SnAgCu		CU Alloy		3		260		С	30	second	s <b>3</b>			
omments														
TTENTION: MSL 3 Rated item	requires Bake and	Dry Pack (after	electrical test)											
or more information regarding m	naterial composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	22.8	mg		Misc.	proprietary data	-	0.0866	mg
			Supplier	Silicon (Si)	7440-21-3		22.4876	mg
			Supplier	Aluminum (Al)	7429-90-5		0.2257	mg
Die Attach	2.19	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.8213	mg
			Supplier	Ethylene Glycol	107-21-1		0.0219	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.0657	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.4599	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.8213	mg
maging Lens	25.2	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		1.26	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		1.26	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		1.26	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		1.26	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.126	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		1.26	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		1.26	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		17.514	mg
Lid Attach	1.42	mg	Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.639	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.284	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.1775	mg
			Supplier	Acrylate Oligomer	Proprietary Data		0.0071	mg
			Supplier	Curative	Proprietary Data		0.0284	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.284	mg
Mold Compound-Black	53.88	mg		Phenolic Resin	proprietary data		8.082	mg
			Supplier	Oxirane	39817-09-9		8.082	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.6164	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5388	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		34.4832	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.0776	mg
Solder Ball	21.74	mg	Supplier	Silver (Ag)	7440-22-4		0.6522	mg
			Supplier	Tin (Sn)	7440-31-5		20.9791	mg
			Supplier	Copper (Cu)	7440-50-8		0.1087	mg
Substrate and Solder Mask	31.5	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		6.6749	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6	0.4126	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9	0.104	mg
			Supplier	Acetophenone Derivative	Proprietary Data	0.6174	mg
			Supplier	Carbon Black (C)	1333-86-4	0.104	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.104	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2	3.0618	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	1.2348	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	1.0584	mg
			Supplier	Copper (Cu)	7440-50-8	14.9341	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	3.1941	mg
Wire Bond - Au	0.27	mg	Supplier	Gold (Au)	7440-57-5	0.27	mg